

Specifications

Designed to support applications such as: SOHO (ADSL Modems), LAN-on-Motherboard (LOM), Hub and Switches. Meets IEEE 802.3 specification.

Materials:

- Housing: Thermoplastic UL94V-0
- Contact/Shield: Copper Alloy
- Shield Plating: Nickel
- Contact Plating: Gold 6µ" min. in contact area
- Wave solder tip temperature: 265°C Max for 5 Sec Max

Electrical Specifications @25°C

Operating Temperature Range: 0°C to 70°C

Turn Ratio (±2%):

$$TX = 1CT:2.5, RX = 1CT:1$$

Inductance OCL:

$$140\mu H \text{ Min @ } 100KHz \text{ } 50mV$$

Insertion Loss:

$$-1.0dB \text{ Max @ } 1.0-10MHz$$

Return Loss:

$$-15dB \text{ Min @ } 1-10MHz$$

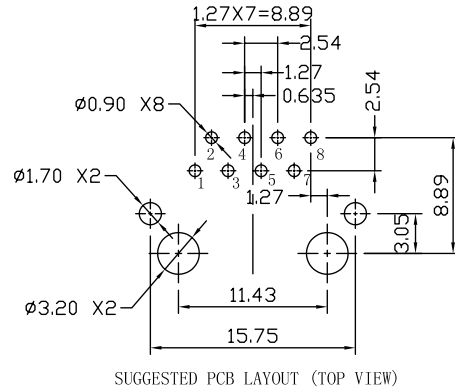
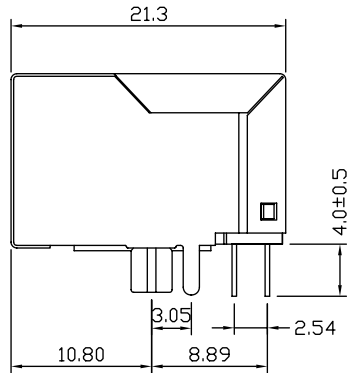
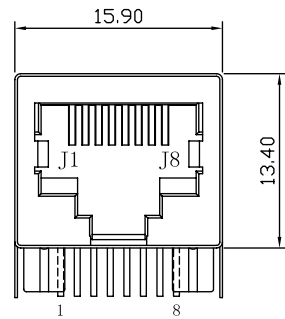
Cross Talk:

$$-30dB \text{ Min @ } 1-10MHz$$

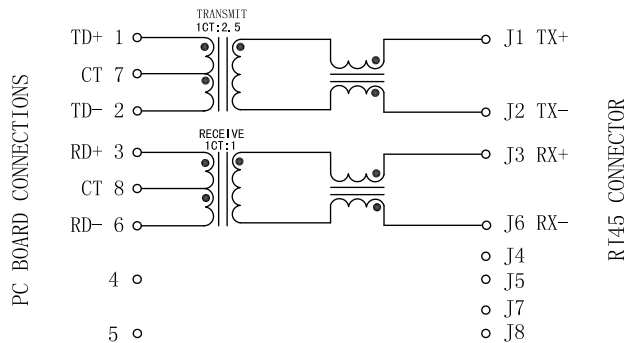
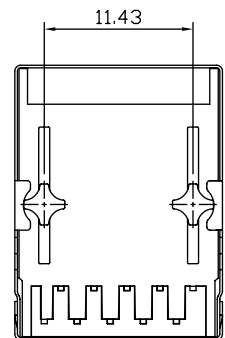
Common Mode Rejection:

$$-25dB \text{ Min @ } 5MHz$$

Hipot Test: 1500Vrms Min



SUGGESTED PCB LAYOUT (TOP VIEW)



General Tolerance	
.X ± 0.30	Angles: ±1°
.XX ± 0.20	
.XXX ± 0.05	
Units : mm	